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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	12696
Number of Logic Elements/Cells	57132
Total RAM Bits	753664
Number of I/O	804
Number of Gates	3263755
Voltage - Supply	1.71V ~ 1.89V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1156-BBGA
Supplier Device Package	1156-FBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xcv2600e-7fg1156c

resources. The abundance of routing resources permits the Virtex-E family to accommodate even the largest and most complex designs.

Virtex-E FPGAs are SRAM-based, and are customized by loading configuration data into internal memory cells. Configuration data can be read from an external SPROM (master serial mode), or can be written into the FPGA (SelectMAP™, slave serial, and JTAG modes).

The standard Xilinx Foundation Series™ and Alliance Series™ Development systems deliver complete design support for Virtex-E, covering every aspect from behavioral and schematic entry, through simulation, automatic design translation and implementation, to the creation and downloading of a configuration bit stream.

Higher Performance

Virtex-E devices provide better performance than previous generations of FPGAs. Designs can achieve synchronous system clock rates up to 240 MHz including I/O or 622 Mb/s using Source Synchronous data transmission architectures. Virtex-E I/Os comply fully with 3.3 V PCI specifications, and interfaces can be implemented that operate at 33 MHz or 66 MHz.

While performance is design-dependent, many designs operate internally at speeds in excess of 133 MHz and can achieve over 311 MHz. Table 2 shows performance data for representative circuits, using worst-case timing parameters.

Table 2: Performance for Common Circuit Functions

Function	Bits	Virtex-E (-7)
Register-to-Register		
Adder	16	4.3 ns
	64	6.3 ns
Pipelined Multiplier	8 x 8	4.4 ns
	16 x 16	5.1 ns
Address Decoder	16	3.8 ns
	64	5.5 ns
16:1 Multiplexer		4.6 ns
Parity Tree	9	3.5 ns
	18	4.3 ns
	36	5.9 ns
Chip-to-Chip		
HSTL Class IV		
LVTTTL, 16mA, fast slew		
LVDS		
LVPECL		

Virtex-E Device/Package Combinations and Maximum I/O

Table 3: Virtex-E Family Maximum User I/O by Device/Package (Excluding Dedicated Clock Pins)

	XCV 50E	XCV 100E	XCV 200E	XCV 300E	XCV 400E	XCV 600E	XCV 1000E	XCV 1600E	XCV 2000E	XCV 2600E	XCV 3200E
CS144	94	94	94								
PQ240	158	158	158	158	158						
HQ240						158	158				
BG352		196	260	260							
BG432				316	316	316					
BG560					404	404	404	404	404		
FG256	176	176	176	176							
FG456			284	312							
FG676					404	444					
FG680						512	512	512	512		
FG860							660	660	660		
FG900						512	660	700			
FG1156							660	724	804	804	804

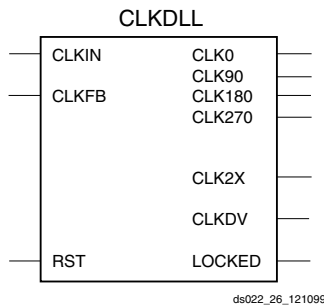


Figure 22: Standard DLL Symbol CLKDLL

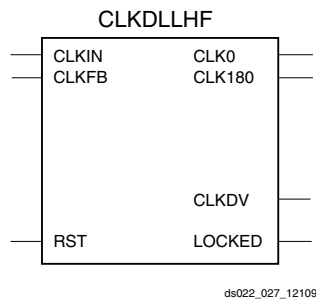


Figure 23: High Frequency DLL Symbol CLKDLLHF

BUFGDLL Pin Descriptions

Use the BUFGDLL macro as the simplest way to provide zero propagation delay for a high-fanout on-chip clock from an external input. This macro uses the IBUFG, CLKDLL and BUFG primitives to implement the most basic DLL application as shown in Figure 24.

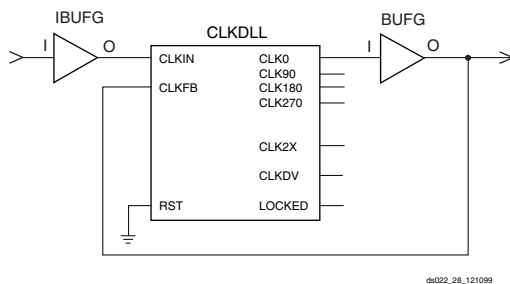


Figure 24: BUFGDLL Schematic

This symbol does not provide access to the advanced clock domain controls or to the clock multiplication or clock division features of the DLL. This symbol also does not provide access to the RST, or LOCKED pins of the DLL. For access to these features, a designer must use the library DLL primitives described in the following sections.

Source Clock Input — I

The I pin provides the user source clock, the clock signal on which the DLL operates, to the BUFGDLL. For the BUFGDLL macro the source clock frequency must fall in the low frequency range as specified in the data sheet. The BUF-

GDLL requires an external signal source clock. Therefore, only an external input port can source the signal that drives the BUFGDLL I pin.

Clock Output — O

The clock output pin O represents a delay-compensated version of the source clock (I) signal. This signal, sourced by a global clock buffer BUFG symbol, takes advantage of the dedicated global clock routing resources of the device.

The output clock has a 50-50 duty cycle unless you deactivate the duty cycle correction property.

CLKDLL Primitive Pin Descriptions

The library CLKDLL primitives provide access to the complete set of DLL features needed when implementing more complex applications with the DLL.

Source Clock Input — CLKIN

The CLKIN pin provides the user source clock (the clock signal on which the DLL operates) to the DLL. The CLKIN frequency must fall in the ranges specified in the data sheet. A global clock buffer (BUFG) driven from another CLKDLL, one of the global clock input buffers (IBUFG), or an IO_LVDS_DLL pin on the same edge of the device (top or bottom) must source this clock signal. There are four IO_LVDS_DLL input pins that can be used as inputs to the DLLs. This makes a total of eight usable input pins for DLLs in the Virtex-E family.

Feedback Clock Input — CLKFB

The DLL requires a reference or feedback signal to provide the delay-compensated output. Connect only the CLK0 or CLK2X DLL outputs to the feedback clock input (CLKFB) pin to provide the necessary feedback to the DLL. The feedback clock input can also be provided through one of the following pins.

IBUFG - Global Clock Input Pad

IO_LVDS_DLL - the pin adjacent to IBUFG

If an IBUFG sources the CLKFB pin, the following special rules apply.

1. An external input port must source the signal that drives the IBUFG I pin.
2. The CLK2X output must feedback to the device if both the CLK0 and CLK2X outputs are driving off chip devices.
3. That signal must directly drive only OBUFs and nothing else.

These rules enable the software determine which DLL clock output sources the CLKFB pin.

Reset Input — RST

When the reset pin RST activates the LOCKED signal deactivates within four source clock cycles. The RST pin, active High, must either connect to a dynamic signal or tied to

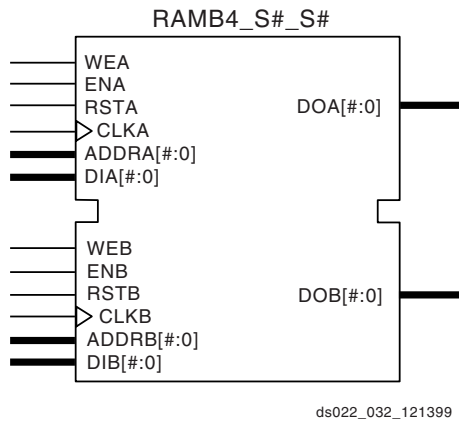


Figure 31: Dual-Port Block SelectRAM+ Memory

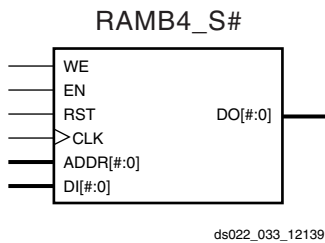


Figure 32: Single-Port Block SelectRAM+ Memory

Table 14: Available Library Primitives

Primitive	Port A Width	Port B Width
RAMB4_S1	1	N/A
RAMB4_S1_S1		1
RAMB4_S1_S2		2
RAMB4_S1_S4		4
RAMB4_S1_S8		8
RAMB4_S1_S16		16
RAMB4_S2	2	N/A
RAMB4_S2_S2		2
RAMB4_S2_S4		4
RAMB4_S2_S8		8
RAMB4_S2_S16		16
RAMB4_S4	4	N/A
RAMB4_S4_S4		4
RAMB4_S4_S8		8
RAMB4_S4_S16		16
RAMB4_S8	8	N/A
RAMB4_S8_S8		8
RAMB4_S8_S16		16
RAMB4_S16	16	N/A
RAMB4_S16_S16		16

Port Signals

Each block SelectRAM+ port operates independently of the others while accessing the same set of 4096 memory cells.

Table 15 describes the depth and width aspect ratios for the block SelectRAM+ memory.

Table 15: Block SelectRAM+ Port Aspect Ratios

Width	Depth	ADDR Bus	Data Bus
1	4096	ADDR<11:0>	DATA<0>
2	2048	ADDR<10:0>	DATA<1:0>
4	1024	ADDR<9:0>	DATA<3:0>
8	512	ADDR<8:0>	DATA<7:0>
16	256	ADDR<7:0>	DATA<15:0>

Clock—CLK[A/B]

Each port is fully synchronous with independent clock pins. All port input pins have setup time referenced to the port CLK pin. The data output bus has a clock-to-out time referenced to the CLK pin.

Enable—EN[A/B]

The enable pin affects the read, write and reset functionality of the port. Ports with an inactive enable pin keep the output pins in the previous state and do not write data to the memory cells.

Write Enable—WE[A/B]

Activating the write enable pin allows the port to write to the memory cells. When active, the contents of the data input bus are written to the RAM at the address pointed to by the address bus, and the new data also reflects on the data out bus. When inactive, a read operation occurs and the contents of the memory cells referenced by the address bus reflect on the data out bus.

Reset—RST[A/B]

The reset pin forces the data output bus latches to zero synchronously. This does not affect the memory cells of the RAM and does not disturb a write operation on the other port.

Address Bus—ADDR[A/B]<#:0>

The address bus selects the memory cells for read or write. The width of the port determines the required width of this bus as shown in Table 15.

Data In Bus—DI[A/B]<#:0>

The data in bus provides the new data value to be written into the RAM. This bus and the port have the same width, as shown in Table 15.

Data Output Bus—DO[AIB]<#:0>

The data out bus reflects the contents of the memory cells referenced by the address bus at the last active clock edge. During a write operation, the data out bus reflects the data in bus. The width of this bus equals the width of the port. The allowed widths appear in [Table 15](#).

Inverting Control Pins

The four control pins (CLK, EN, WE and RST) for each port have independent inversion control as a configuration option.

Address Mapping

Each port accesses the same set of 4096 memory cells using an addressing scheme dependent on the width of the port.

The physical RAM location addressed for a particular width are described in the following formula (of interest only when the two ports use different aspect ratios).

$$\text{Start} = ((\text{ADDR}_{\text{port}} + 1) * \text{Width}_{\text{port}}) - 1$$

$$\text{End} = \text{ADDR}_{\text{port}} * \text{Width}_{\text{port}}$$

Conflict Resolution

The block SelectRAM+ memory is a true dual-read/write port RAM that allows simultaneous access of the same memory cell from both ports. When one port writes to a given memory cell, the other port must not address that memory cell (for a write or a read) within the clock-to-clock setup window. The following lists specifics of port and memory cell write conflict resolution.

- If both ports write to the same memory cell simultaneously, violating the clock-to-clock setup requirement, consider the data stored as invalid.
- If one port attempts a read of the same memory cell the other simultaneously writes, violating the clock-to-clock setup requirement, the following occurs.
 - The write succeeds
 - The data out on the writing port accurately reflects the data written.
 - The data out on the reading port is invalid.

Conflicts do not cause any physical damage.

[Table 16](#) shows low order address mapping for each port width.

Table 16: Port Address Mapping

Port Width	Port Addresses																
1	4095...	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
2	2047...	07		06		05		04		03		02		01		00	
4	1023...	03				02				01				00			
8	511...	01								00							
16	255...	00															

Creating Larger RAM Structures

The block SelectRAM+ columns have specialized routing to allow cascading blocks together with minimal routing delays. This achieves wider or deeper RAM structures with a smaller timing penalty than when using normal routing channels.

Location Constraints

Block SelectRAM+ instances can have LOC properties attached to them to constrain the placement. The block SelectRAM+ placement locations are separate from the CLB location naming convention, allowing the LOC properties to transfer easily from array to array.

The LOC properties use the following form.

$$\text{LOC} = \text{RAMB4_R\#C\#}$$

RAMB4_R0C0 is the upper left RAMB4 location on the device.

Single Port Timing

[Figure 33](#) shows a timing diagram for a single port of a block SelectRAM+ memory. The block SelectRAM+ AC switching characteristics are specified in the data sheet. The block SelectRAM+ memory is initially disabled.

At the first rising edge of the CLK pin, the ADDR, DI, EN, WE, and RST pins are sampled. The EN pin is High and the WE pin is Low indicating a read operation. The DO bus contains the contents of the memory location, 0x00, as indicated by the ADDR bus.

At the second rising edge of the CLK pin, the ADDR, DI, EN, WR, and RST pins are sampled again. The EN and WE pins are High indicating a write operation. The DO bus mirrors the DI bus. The DI bus is written to the memory location 0x0F.

At the third rising edge of the CLK pin, the ADDR, DI, EN, WR, and RST pins are sampled again. The EN pin is High and the WE pin is Low indicating a read operation. The DO bus contains the contents of the memory location 0x7E as indicated by the ADDR bus.

At the fourth rising edge of the CLK pin, the ADDR, DI, EN, WR, and RST pins are sampled again. The EN pin is Low

SSTL2_II

A sample circuit illustrating a valid termination technique for SSTL2_II appears in Figure 52. DC voltage specifications appear in Table 31.

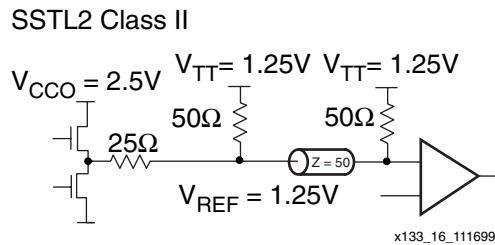


Figure 52: Terminated SSTL2 Class II

Table 31: SSTL2_II Voltage Specifications

Parameter	Min	Typ	Max
V_{CCO}	2.3	2.5	2.7
$V_{REF} = 0.5 \times V_{CCO}$	1.15	1.25	1.35
$V_{TT} = V_{REF} + N^{(1)}$	1.11	1.25	1.39
$V_{IH} = V_{REF} + 0.18$	1.33	1.43	3.0 ⁽²⁾
$V_{IL} = V_{REF} - 0.18$	-0.3 ⁽³⁾	1.07	1.17
$V_{OH} = V_{REF} + 0.8$	1.95	-	-
$V_{OL} = V_{REF} - 0.8$	-	-	0.55
I_{OH} at V_{OH} (mA)	-15.2	-	-
I_{OL} at V_{OL} (mA)	15.2	-	-

Notes:

1. N must be greater than or equal to -0.04 and less than or equal to 0.04.
2. V_{IH} maximum is $V_{CCO} + 0.3$.
3. V_{IL} minimum does not conform to the formula.

CTT

A sample circuit illustrating a valid termination technique for CTT appear in Figure 53. DC voltage specifications appear in Table 32.

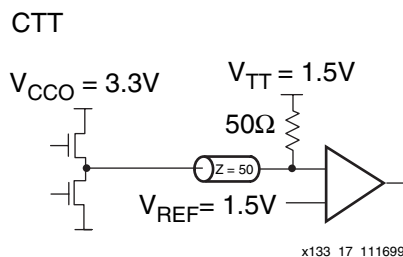


Figure 53: Terminated CTT

Table 32: CTT Voltage Specifications

Parameter	Min	Typ	Max
V_{CCO}	2.05 ⁽¹⁾	3.3	3.6
V_{REF}	1.35	1.5	1.65
V_{TT}	1.35	1.5	1.65
$V_{IH} = V_{REF} + 0.2$	1.55	1.7	-
$V_{IL} = V_{REF} - 0.2$	-	1.3	1.45
$V_{OH} = V_{REF} + 0.4$	1.75	1.9	-
$V_{OL} = V_{REF} - 0.4$	-	1.1	1.25
I_{OH} at V_{OH} (mA)	-8	-	-
I_{OL} at V_{OL} (mA)	8	-	-

Notes:

1. Timing delays are calculated based on V_{CCO} min of 3.0V.

PCI33_3 & PCI66_3

PCI33_3 or PCI66_3 require no termination. DC voltage specifications appear in Table 33.

Table 33: PCI33_3 and PCI66_3 Voltage Specifications

Parameter	Min	Typ	Max
V_{CCO}	3.0	3.3	3.6
V_{REF}	-	-	-
V_{TT}	-	-	-
$V_{IH} = 0.5 \times V_{CCO}$	1.5	1.65	$V_{CCO} + 0.5$
$V_{IL} = 0.3 \times V_{CCO}$	-0.5	0.99	1.08
$V_{OH} = 0.9 \times V_{CCO}$	2.7	-	-
$V_{OL} = 0.1 \times V_{CCO}$	-	-	0.36
I_{OH} at V_{OH} (mA)	Note 1	-	-
I_{OL} at V_{OL} (mA)	Note 1	-	-

Notes:

1. Tested according to the relevant specification.

IOB Output Switching Characteristics, Figure 1

Output delays terminating at a pad are specified for LVTTTL with 12 mA drive and fast slew rate. For other standards, adjust the delays with the values shown in **IOB Output Switching Characteristics Standard Adjustments**, page 10.

		Speed Grade ⁽¹⁾				Units
Description ⁽²⁾	Symbol	Min	-8	-7	-6	
Propagation Delays						
O input to Pad	T _{IOOP}	1.04	2.5	2.7	2.9	ns, max
O input to Pad via transparent latch	T _{IOOLP}	1.24	2.9	3.1	3.4	ns, max
3-State Delays						
T input to Pad high-impedance (Note 2)	T _{IOTHZ}	0.73	1.5	1.7	1.9	ns, max
T input to valid data on Pad	T _{IOTON}	1.13	2.7	2.9	3.1	ns, max
T input to Pad high-impedance via transparent latch (Note 2)	T _{IOTLPHZ}	0.86	1.8	2.0	2.2	ns, max
T input to valid data on Pad via transparent latch	T _{IOTLPON}	1.26	3.0	3.2	3.4	ns, max
GTS to Pad high impedance (Note 2)	T _{GTS}	1.94	4.1	4.6	4.9	ns, max
Sequential Delays						
Clock CLK						
Minimum Pulse Width, High	T _{CH}	0.56	1.2	1.3	1.4	ns, min
Minimum Pulse Width, Low	T _{CL}	0.56	1.2	1.3	1.4	ns, min
Clock CLK to Pad	T _{IOCKP}	0.97	2.4	2.8	2.9	ns, max
Clock CLK to Pad high-impedance (synchronous) (Note 2)	T _{IOCKHZ}	0.77	1.6	2.0	2.2	ns, max
Clock CLK to valid data on Pad (synchronous)	T _{IOCKON}	1.17	2.8	3.2	3.4	ns, max
Setup and Hold Times before/after Clock CLK						
O input	T _{IOOCK} / T _{IOCKO}	0.43 / 0	0.9 / 0	1.0 / 0	1.1 / 0	ns, min
OCE input	T _{IOOCECK} / T _{IOCKOCE}	0.28 / 0	0.55 / 0.01	0.7 / 0	0.7 / 0	ns, min
SR input (OFF)	T _{IOSRCKO} / T _{IOCKOSR}	0.40 / 0	0.8 / 0	0.9 / 0	1.0 / 0	ns, min
3-State Setup Times, T input	T _{IOTCK} / T _{IOCKT}	0.26 / 0	0.51 / 0	0.6 / 0	0.7 / 0	ns, min
3-State Setup Times, TCE input	T _{IOTCECK} / T _{IOCKTCE}	0.30 / 0	0.6 / 0	0.7 / 0	0.8 / 0	ns, min
3-State Setup Times, SR input (TFF)	T _{IOSRCKT} / T _{IOCKTSR}	0.38 / 0	0.8 / 0	0.9 / 0	1.0 / 0	ns, min
Set/Reset Delays						
SR input to Pad (asynchronous)	T _{IOSRP}	1.30	3.1	3.3	3.5	ns, max
SR input to Pad high-impedance (asynchronous) (Note 2)	T _{IOSRHZ}	1.08	2.2	2.4	2.7	ns, max
SR input to valid data on Pad (asynchronous)	T _{IOSRON}	1.48	3.4	3.7	3.9	ns, max
GSR to Pad	T _{IOGSRQ}	3.88	7.6	8.5	9.7	ns, max

Notes:

1. A Zero "0" Hold Time listing indicates no hold time or a negative hold time. Negative values can not be guaranteed "best-case", but if a "0" is listed, there is no positive hold time.
2. 3-state turn-off delays should not be adjusted.

CLB Switching Characteristics

Delays originating at F/G inputs vary slightly according to the input used, see [Figure 2](#). The values listed below are worst-case. Precise values are provided by the timing analyzer.

		Speed Grade ⁽¹⁾				Units
Description	Symbol	Min	-8	-7	-6	
Combinatorial Delays						
4-input function: F/G inputs to X/Y outputs	T _{ILO}	0.19	0.40	0.42	0.47	ns, max
5-input function: F/G inputs to F5 output	T _{IF5}	0.36	0.76	0.8	0.9	ns, max
5-input function: F/G inputs to X output	T _{IF5X}	0.35	0.74	0.8	0.9	ns, max
6-input function: F/G inputs to Y output via F6 MUX	T _{IF6Y}	0.35	0.74	0.9	1.0	ns, max
6-input function: F5IN input to Y output	T _{F5INY}	0.04	0.11	0.20	0.22	ns, max
Incremental delay routing through transparent latch to XQ/YQ outputs	T _{IFNCTL}	0.27	0.63	0.7	0.8	ns, max
BY input to YB output	T _{BYYB}	0.19	0.38	0.46	0.51	ns, max
Sequential Delays						
FF Clock CLK to XQ/YQ outputs	T _{CKO}	0.34	0.78	0.9	1.0	ns, max
Latch Clock CLK to XQ/YQ outputs	T _{CKLO}	0.40	0.77	0.9	1.0	ns, max
Setup and Hold Times before/after Clock CLK						
4-input function: F/G Inputs	T _{ICK} / T _{CKI}	0.39 / 0	0.9 / 0	1.0 / 0	1.1 / 0	ns, min
5-input function: F/G inputs	T _{IF5CK} / T _{CKIF5}	0.55 / 0	1.3 / 0	1.4 / 0	1.5 / 0	ns, min
6-input function: F5IN input	T _{F5INCK} / T _{CKF5IN}	0.27 / 0	0.6 / 0	0.8 / 0	0.8 / 0	ns, min
6-input function: F/G inputs via F6 MUX	T _{IF6CK} / T _{CKIF6}	0.58 / 0	1.3 / 0	1.5 / 0	1.6 / 0	ns, min
BX/BY inputs	T _{DICK} / T _{CKDI}	0.25 / 0	0.6 / 0	0.7 / 0	0.8 / 0	ns, min
CE input	T _{CECK} / T _{CKCE}	0.28 / 0	0.55 / 0	0.7 / 0	0.7 / 0	ns, min
SR/BY inputs (synchronous)	T _{RCK} / T _{CKR}	0.24 / 0	0.46 / 0	0.52 / 0	0.6 / 0	ns, min
Clock CLK						
Minimum Pulse Width, High	T _{CH}	0.56	1.2	1.3	1.4	ns, min
Minimum Pulse Width, Low	T _{CL}	0.56	1.2	1.3	1.4	ns, min
Set/Reset						
Minimum Pulse Width, SR/BY inputs	T _{RPW}	0.94	1.9	2.1	2.4	ns, min
Delay from SR/BY inputs to XQ/YQ outputs (asynchronous)	T _{RQ}	0.39	0.8	0.9	1.0	ns, max
Toggle Frequency (MHz) (for export control)	F _{TOG}	-	416	400	357	MHz

Notes:

1. A Zero "0" Hold Time listing indicates no hold time or a negative hold time. Negative values can not be guaranteed "best-case", but if a "0" is listed, there is no positive hold time.

Low Voltage Differential Signals

The Virtex-E family incorporates low-voltage signalling (LVDS and LVPECL). Two pins are utilized for these signals to be connected to a Virtex-E device. These are known as differential pin pairs. Each differential pin pair has a Positive (P) and a Negative (N) pin. These pairs are labeled in the following manner.

IO_L#[P/N]

where

L = LVDS or LVPECL pin

= Pin Pair Number

P = Positive

N = Negative

I/O pins for differential signals can either be synchronous or asynchronous, input or output. The pin pairs can be used for synchronous input and output signals as well as asynchronous input signals. However, only some of the low-voltage pairs can be used for asynchronous output signals.

Differential signals require the pins of a pair to switch almost simultaneously. If the signals driving the pins are from IOB flip-flops, they are synchronous. If the signals driving the pins are from internal logic, they are asynchronous. [Table 2](#) defines the names and function of the different types of low-voltage pin pairs in the Virtex-E family.

Table 2: LVDS Pin Pairs

Pin Name	Description
IO_L#[P/N] Example: IO_L22N	Represents a general IO or a synchronous input/output differential signal. When used as a differential signal, N means Negative I/O and P means Positive I/O.
IO_L#[P/N]_Y Example: IO_L22N_Y	Represents a general IO or a synchronous input/output differential signal, or a part-dependent asynchronous output differential signal.
IO_L#[P/N]_YY Example: O_L22N_YY	Represents a general IO or a synchronous input/output differential signal, or an asynchronous output differential signal.
IO_LVDS_DLL_L#[P/N] Example: IO_LVDS_DLL_L16N	Represents a general IO or a synchronous input/output differential signal, a differential clock input signal, or a DLL input. When used as a differential clock input, this pin is paired with the adjacent GCK pin. The GCK pin is always the positive input in the differential clock input configuration.

Virtex-E Package Pinouts

The Virtex-E family of FPGAs is available in 12 popular packages, including chip-scale, plastic and high heat-dissipation quad flat packs, and ball grid and fine-pitch ball grid arrays. Family members have footprint compatibility across devices provided in the same package. The pinout tables in

this section indicate function, pin, and bank information for each package/device combination. Following each pinout table is an additional table summarizing information specific to differential pin pairs for all devices provided in that package.

Table 12: BG432 — XCV300E, XCV400E, XCV600E

Bank	Pin Description	Pin #
7	IO_L132P_Y	G28
7	IO_L133N	E31
7	IO_L133P	E30
7	IO_L134N_Y	F29
7	IO_VREF_L134P_Y	F28
7	IO_L135N_Y	D31
7	IO_L135P_Y	D30
7	IO_L136N	E29
7	IO_L136P	E28
2	CCLK	D4
3	DONE	AH4
NA	DXN	AH27
NA	DXP	AK29
NA	M0	AH28
NA	M1	AH29
NA	M2	AJ28
NA	PROGRAM	AH3
NA	TCK	D28
NA	TDI	B3
2	TDO	C4
NA	TMS	D29
NA	VCCINT	A10
NA	VCCINT	A17
NA	VCCINT	B23
NA	VCCINT	B26
NA	VCCINT	C7
NA	VCCINT	C14
NA	VCCINT	C19
NA	VCCINT	F1
NA	VCCINT	F30
NA	VCCINT	K3
NA	VCCINT	K29
NA	VCCINT	N2
NA	VCCINT	N29

Table 12: BG432 — XCV300E, XCV400E, XCV600E

Bank	Pin Description	Pin #
NA	VCCINT	T1
NA	VCCINT	T29
NA	VCCINT	W2
NA	VCCINT	W31
NA	VCCINT	AB2
NA	VCCINT	AB30
NA	VCCINT	AE29
NA	VCCINT	AF1
NA	VCCINT	AH8
NA	VCCINT	AH24
NA	VCCINT	AJ10
NA	VCCINT	AJ16
NA	VCCINT	AK22
NA	VCCINT	AK13
NA	VCCINT	AK19
0	VCCO	A21
0	VCCO	C29
0	VCCO	D21
1	VCCO	A1
1	VCCO	A11
1	VCCO	D11
2	VCCO	C3
2	VCCO	L4
2	VCCO	L1
3	VCCO	AA1
3	VCCO	AA4
3	VCCO	AJ3
4	VCCO	AH11
4	VCCO	AL1
4	VCCO	AL11
5	VCCO	AH21
5	VCCO	AL21
5	VCCO	AJ29
6	VCCO	AA28
6	VCCO	AA31

BG432 Differential Pin Pairs

Virtex-E devices have differential pin pairs that can also provide other functions when not used as a differential pair. A ✓ in the AO column indicates that the pin pair can be used as an asynchronous output for all devices provided in this package. Pairs with a note number in the AO column are device dependent. They can have asynchronous outputs if the pin pair are in the same CLB row and column in the device. Numbers in this column refer to footnotes that indicate which devices have pin pairs that can be asynchronous outputs. The Other Functions column indicates alternative function(s) not available when the pair is used as a differential pair or differential clock.

Table 13: BG432 Differential Pin Pair Summary
XCV300E, XCV400E, XC600E

Pair	Bank	P Pin	N Pin	AO	Other Functions
Global Differential Clock					
0	4	AL16	AH15	NA	IO_DLL_L86P
1	5	AK16	AL17	NA	IO_DLL_L86N
2	1	A16	B16	NA	IO_DLL_L16P
3	0	D17	C17	NA	IO_DLL_L16N
IO LVDS					
Total Outputs: 137, Asynchronous Output Pairs: 63					
0	0	D27	B29	1	-
1	0	C27	B28	✓	-
2	0	A28	D26	✓	VREF
3	0	C26	B27	2	-
4	0	A27	D25	✓	-
5	0	C25	D24	✓	VREF
6	0	D23	B25	1	-
7	0	B24	C24	1	VREF
8	0	A24	D22	✓	VREF
9	0	B22	C22	✓	-
10	0	D20	C21	✓	-
11	0	C20	B21	✓	-
12	0	D19	A20	✓	-
13	0	A19	B19	✓	VREF
14	0	D18	B18	1	-
15	0	B17	C18	1	VREF

Table 13: BG432 Differential Pin Pair Summary
XCV300E, XCV400E, XC600E

Pair	Bank	P Pin	N Pin	AO	Other Functions
16	1	B16	C17	NA	IO_LVDS_DLL
17	1	B15	A15	1	VREF
18	1	D15	C15	1	-
19	1	A13	B14	✓	VREF
20	1	D14	B13	✓	-
21	1	B12	C13	✓	-
22	1	C12	D13	✓	-
23	1	C11	D12	✓	-
24	1	C10	B10	✓	VREF
25	1	D10	C9	1	VREF
26	1	B8	A8	1	-
27	1	B7	C8	✓	VREF
28	1	A6	D8	✓	-
29	1	D7	B6	2	-
30	1	C6	A5	✓	VREF
31	1	D6	B5	✓	-
32	1	C5	A4	1	-
33	1	D5	B4	✓	CS, WRITE
34	2	D3	C2	✓	DIN, D0, BUSY
35	2	D2	E4	3	-
36	2	D1	E3	4	-
37	2	E2	F4	1	VREF
38	2	E1	F3	5	-
39	2	F2	G4	1	-
40	2	G3	G2	✓	VREF
41	2	H3	H2	4	-
42	2	H1	J4	1	VREF
43	2	J2	K4	✓	D1
44	2	K2	K1	✓	D2
45	2	L2	M4	4	-
46	2	M3	M2	1	-
47	2	N4	N3	1	-

Table 14: BG560 — XCV400E, XCV600E, XCV1000E, XCV1600E, XCV2000E

Bank	Pin Description	Pin#	See Note
0	IO_L11P_YY	B24	
0	IO_L12N_Y	E22	
0	IO_L12P_Y	C23	
0	IO_L13N_YY	A23	
0	IO_L13P_YY	D22	
0	IO_VREF_L14N_YY	E21	3
0	IO_L14P_YY	B22	
0	IO_L15N_Y	D21	
0	IO_L15P_Y	C21	
0	IO_L16N_YY	B21	
0	IO_L16P_YY	E20	
0	IO_VREF_L17N_YY	D20	
0	IO_L17P_YY	C20	
0	IO_L18N_Y	B20	
0	IO_L18P_Y	E19	
0	IO_L19N_Y	D19	
0	IO_L19P_Y	C19	
0	IO_VREF_L20N_Y	A19	
0	IO_L20P_Y	D18	
0	IO_LVDS_DLL_L21N	C18	
0	IO_VREF	E18	2
1	GCK2	D17	
1	IO	A3	
1	IO	D9	
1	IO	E8	
1	IO	E11	
1	IO_LVDS_DLL_L21P	E17	
1	IO_VREF_L22N_Y	C17	2
1	IO_L22P_Y	B17	
1	IO_L23N_Y	B16	
1	IO_VREF_L23P_Y	D16	
1	IO_L24N_Y	E16	
1	IO_L24P_Y	C16	
1	IO_L25N_Y	A15	

Table 14: BG560 — XCV400E, XCV600E, XCV1000E, XCV1600E, XCV2000E

Bank	Pin Description	Pin#	See Note
1	IO_L25P_Y	C15	
1	IO_L26N_YY	D15	
1	IO_VREF_L26P_YY	E15	
1	IO_L27N_YY	C14	
1	IO_L27P_YY	D14	
1	IO_L28N_Y	A13	
1	IO_L28P_Y	E14	
1	IO_L29N_YY	C13	
1	IO_VREF_L29P_YY	D13	3
1	IO_L30N_YY	C12	
1	IO_L30P_YY	E13	
1	IO_L31N_Y	A11	
1	IO_L31P_Y	D12	
1	IO_L32N_YY	B11	
1	IO_L32P_YY	C11	
1	IO_L33N_YY	B10	
1	IO_VREF_L33P_YY	D11	
1	IO_L34N_Y	C10	
1	IO_L34P_Y	A9	
1	IO_L35N_Y	C9	
1	IO_VREF_L35P_Y	D10	4
1	IO_L36N_Y	A8	
1	IO_L36P_Y	B8	
1	IO_L37N_Y	E10	
1	IO_VREF_L37P_Y	C8	1
1	IO_L38N_YY	B7	
1	IO_VREF_L38P_YY	A6	
1	IO_L39N_YY	C7	
1	IO_L39P_YY	D8	
1	IO_L40N_Y	A5	
1	IO_L40P_Y	B5	
1	IO_L41N_YY	C6	
1	IO_VREF_L41P_YY	D7	
1	IO_L42N_YY	A4	
1	IO_L42P_YY	B4	

Table 14: BG560 — XCV400E, XCV600E, XCV1000E, XCV1600E, XCV2000E

Bank	Pin Description	Pin#	See Note
3	IO_D4_L73P_YY	W4	
3	IO_VREF_L73N_YY	W5	
3	IO_L74P_Y	Y3	
3	IO_L74N_Y	Y4	
3	IO_L75P_Y	AA1	
3	IO_L75N_Y	Y5	
3	IO_L76P_Y	AA3	
3	IO_VREF_L76N_Y	AA4	3
3	IO_L77P_Y	AB3	
3	IO_L77N_Y	AA5	
3	IO_L78P_Y	AC1	
3	IO_L78N_Y	AB4	
3	IO_L79P_YY	AC3	
3	IO_D5_L79N_YY	AB5	
3	IO_D6_L80P_YY	AC4	
3	IO_VREF_L80N_YY	AD3	
3	IO_L81P_Y	AE1	
3	IO_L81N_Y	AC5	
3	IO_L82P_Y	AD4	
3	IO_VREF_L82N_Y	AF1	4
3	IO_L83P_Y	AF2	
3	IO_L83N_Y	AD5	
3	IO_L84P_Y	AG2	
3	IO_VREF_L84N_Y	AE4	1
3	IO_L85P_YY	AH1	
3	IO_VREF_L85N_YY	AE5	
3	IO_L86P_Y	AF4	
3	IO_L86N_Y	AJ1	
3	IO_L87P_Y	AJ2	
3	IO_L87N_Y	AF5	
3	IO_L88P_Y	AG4	
3	IO_VREF_L88N_Y	AK2	
3	IO_L89P_Y	AJ3	
3	IO_L89N_Y	AG5	
3	IO_L90P_Y	AL1	

Table 14: BG560 — XCV400E, XCV600E, XCV1000E, XCV1600E, XCV2000E

Bank	Pin Description	Pin#	See Note
3	IO_VREF_L90N_Y	AH4	3
3	IO_D7_L91P_YY	AJ4	
3	IO_INIT_L91N_YY	AH5	
3	IO	U4	
4	GCK0	AL17	
4	IO	AJ8	
4	IO	AJ11	
4	IO	AK6	
4	IO	AK9	
4	IO_L92P_YY	AL4	
4	IO_L92N_YY	AJ6	
4	IO_L93P_Y	AK5	
4	IO_VREF_L93N_Y	AN3	3
4	IO_L94P_YY	AL5	
4	IO_L94N_YY	AJ7	
4	IO_VREF_L95P_YY	AM4	
4	IO_L95N_YY	AM5	
4	IO_L96P_Y	AK7	
4	IO_L96N_Y	AL6	
4	IO_L97P_YY	AM6	
4	IO_L97N_YY	AN6	
4	IO_VREF_L98P_YY	AL7	
4	IO_L98N_YY	AJ9	
4	IO_L99P_Y	AN7	
4	IO_VREF_L99N_Y	AL8	1
4	IO_L100P_Y	AM8	
4	IO_L100N_Y	AJ10	
4	IO_VREF_L101P_Y	AL9	4
4	IO_L101N_Y	AM9	
4	IO_L102P_Y	AK10	
4	IO_L102N_Y	AN9	
4	IO_VREF_L103P_YY	AL10	
4	IO_L103N_YY	AM10	
4	IO_L104P_YY	AL11	

BG560 Differential Pin Pairs

Virtex-E devices have differential pin pairs that can also provide other functions when not used as a differential pair. A ✓ in the AO column indicates that the pin pair can be used as an asynchronous output for all devices provided in this package. Pairs with a note number in the AO column are device dependent. They can have asynchronous outputs if the pin pair are in the same CLB row and column in the device. Numbers in this column refer to footnotes that indicate which devices have pin pairs that can be asynchronous outputs. The Other Functions column indicates alternative function(s) not available when the pair is used as a differential pair or differential clock.

Table 15: BG560 Differential Pin Pair Summary
XCV400E, XCV600E, XCV1000E, XCV1600E, XCV2000E

Pair	Bank	P Pin	N Pin	AO	Other Functions
Global Differential Clock					
0	4	AL17	AM17	NA	IO_DLL_L15P
1	5	AJ17	AM18	NA	IO_DLL_L15N
2	1	D17	E17	NA	IO_DLL_L21P
3	0	A17	C18	NA	IO_DLL_L21N
IO LVDS					
Total Outputs: 183, Asynchronous Outputs: 87					
0	0	D29	E28	8	VREF
1	0	A31	D28	✓	-
2	0	C29	E27	✓	VREF
3	0	D27	B30	3	-
4	0	B29	E26	✓	-
5	0	C27	D26	✓	VREF
6	0	A28	E25	9	VREF
7	0	C26	D25	7	-
8	0	B26	E24	7	VREF
9	0	D24	C25	2	-
10	0	A25	E23	✓	VREF
11	0	B24	D23	✓	-
12	0	C23	E22	8	-
13	0	D22	A23	✓	-
14	0	B22	E21	✓	VREF
15	0	C21	D21	3	-

Table 15: BG560 Differential Pin Pair Summary
XCV400E, XCV600E, XCV1000E, XCV1600E, XCV2000E

Pair	Bank	P Pin	N Pin	AO	Other Functions
16	0	E20	B21	✓	-
17	0	C20	D20	✓	VREF
18	0	E19	B20	9	-
19	0	C19	D19	7	-
20	0	D18	A19	7	VREF
21	1	E17	C18	NA	IO_LVDS_DLL
22	1	B17	C17	2	VREF
23	1	D16	B16	7	VREF
24	1	C16	E16	7	-
25	1	C15	A15	9	-
26	1	E15	D15	✓	VREF
27	1	D14	C14	✓	-
28	1	E14	A13	3	-
29	1	D13	C13	✓	VREF
30	1	E13	C12	✓	-
31	1	D12	A11	8	-
32	1	C11	B11	✓	-
33	1	D11	B10	✓	VREF
34	1	A9	C10	10	-
35	1	D10	C9	7	VREF
36	1	B8	A8	7	-
37	1	C8	E10	5	VREF
38	1	A6	B7	✓	VREF
39	1	D8	C7	✓	-
40	1	B5	A5	11	-
41	1	D7	C6	✓	VREF
42	1	B4	A4	✓	-
43	1	E7	C5	12	VREF
44	1	A2	D6	✓	CS
45	2	D4	E4	✓	DIN, D0
46	2	F5	B3	17	VREF

Table 16: FG256 Package — XCV50E, XCV100E, XCV200E, XCV300E

Bank	Pin Description	Pin #
1	IO_L11N_Y	A10
1	IO_L11P_Y	D10
1	IO_L12N_YY	C10
1	IO_L12P_YY	A11
1	IO_L13N_YY	B11
1	IO_VREF_L13P_YY	E11 ¹
1	IO_L14N_Y	A12
1	IO_L14P_Y	D11
1	IO_L15N_YY	A13
1	IO_VREF_L15P_YY	C11
1	IO_L16N_YY	B12
1	IO_L16P_YY	D12
1	IO_VREF_L17N_Y	A14 ²
1	IO_L17P_Y	C12
1	IO_WRITE_L18N_YY	C13
1	IO_CS_L18P_YY	B13
2	IO_DOUT_BUSY_L19P_YY	C15
2	IO_DIN_D0_L19N_YY	D14
2	IO_L20P	B16
2	IO_VREF_L20N	E13 ²
2	IO_L21P_YY	C16
2	IO_L21N_YY	E14
2	IO_VREF_L22P_Y	F13
2	IO_L22N_Y	E15
2	IO_L23P	F12
2	IO_L23N	D16
2	IO_VREF_L24P_Y	F14 ¹
2	IO_D1_L24N_Y	E16
2	IO_D2_L25P_YY	F15
2	IO_L25N_YY	G13
2	IO_L26P	F16
2	IO_L26N	G12
2	IO_L27P_YY	G15
2	IO_L27N_YY	G14

Table 16: FG256 Package — XCV50E, XCV100E, XCV200E, XCV300E

Bank	Pin Description	Pin #
2	IO_VREF_L28P_Y	H13
2	IO_D3_L28N_Y	G16
2	IO_L29P	J13
2	IO_L29N	H15
2	IO_L30P_YY	H14
2	IO_L30N_YY	H16
3	IO	J15
3	IO_L31P	K15
3	IO_L31N	J14
3	IO_D4_L32P_Y	J16
3	IO_VREF_L32N_Y	K16
3	IO_L33P_YY	K12
3	IO_L33N_YY	L15
3	IO_L34P	K13
3	IO_L34N	L16
3	IO_L35P_YY	K14
3	IO_D5_L35N_YY	M16
3	IO_D6_L36P_Y	N16
3	IO_VREF_L36N_Y	L13 ¹
3	IO_L37P	P16
3	IO_L37N	L12
3	IO_L38P_Y	M15
3	IO_VREF_L38N_Y	L14
3	IO_L39P_YY	M14
3	IO_L39N_YY	R16
3	IO_VREF_L40P	M13 ²
3	IO_L40N	T15
3	IO_D7_L41P_YY	N14
3	IO_INIT_L41N_YY	N15
4	GCK0	N8
4	IO	P10
4	IO_L42P_YY	T14
4	IO_L42N_YY	P13

Table 24: FG860 — XCV1000E, XCV1600E, XCV2000E

Bank	Pin Description	Pin #
5	IO_L178P_Y	BB23
5	IO_L178N_Y	AW23
5	IO_L179P_YY	AV23
5	IO_VREF_L179N_YY	BA23
5	IO_L180P_YY	AW24
5	IO_L180N_YY	BB24
5	IO_L181P_Y	AY24
5	IO_L181N_Y	AW25
5	IO_L182P_Y	BA24
5	IO_L182N_Y	AV25
5	IO_L183P_YY	AW26
5	IO_VREF_L183N_YY	AY25
5	IO_L184P_YY	AV26
5	IO_L184N_YY	BA25
5	IO_L185P_Y	BB26
5	IO_L185N_Y	AV27
5	IO_L186P_Y	AY26
5	IO_L186N_Y	AU27
5	IO_L187P_YY	AW28
5	IO_VREF_L187N_YY	BB27
5	IO_L188P_YY	AY27
5	IO_L188N_YY	AV28
5	IO_L189P_Y	BA27
5	IO_L189N_Y	AW29
5	IO_L190P_Y	BB28
5	IO_L190N_Y	AV29
5	IO_L191P_Y	AY28
5	IO_L191N_Y	AW30
5	IO_L192P_Y	BA28
5	IO_L192N_Y	AW31
5	IO_L193P_YY	BB29
5	IO_L193N_YY	AV31
5	IO_L194P_YY	AY29
5	IO_VREF_L194N_YY	AY32
5	IO_L195P_Y	AW32
5	IO_L195N_Y	BB30
5	IO_L196P_Y	AV32

Table 24: FG860 — XCV1000E, XCV1600E, XCV2000E

Bank	Pin Description	Pin #
5	IO_L196N_Y	AY30
5	IO_L197P_YY	BA30
5	IO_VREF_L197N_YY	AW33
5	IO_L198P_YY	BB31
5	IO_L198N_YY	AV33
5	IO_L199P_Y	AY34
5	IO_VREF_L199N_Y	BA31 ²
5	IO_L200P_Y	AW34
5	IO_L200N_Y	BB32
5	IO_L201P_YY	BA32
5	IO_VREF_L201N_YY	AY35
5	IO_L202P_YY	BB33
5	IO_L202N_YY	AW35
5	IO_L203P_Y	AV35
5	IO_L203N_Y	BB34
5	IO_L204P_Y	AY36
5	IO_L204N_Y	BA34
5	IO_L205P_YY	BB35
5	IO_VREF_L205N_YY	AV36
5	IO_L206P_YY	BA35
5	IO_L206N_YY	AY37
5	IO_L207P_Y	BB36
5	IO_L207N_Y	BA36
5	IO_L208P_Y	AW37
5	IO_VREF_L208N_Y	BB37
5	IO_L209P_Y	BA37
5	IO_L209N_Y	AY38
5	IO_L210P_Y	BB38
5	IO_L210N_Y	AY39
6	IO	AA40
6	IO	AB41
6	IO	AC42
6	IO	AD39
6	IO	AE40
6	IO	AF38
6	IO	AF40

Table 28: FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E

Bank	Pin Description	Pin #
2	IO_L126N_YY	T32
2	IO_VREF_L127P_Y	U29 ¹
2	IO_L127N_Y	U33
2	IO_L128P_YY	V33
2	IO_L128N_YY	U31
3	IO	V27 ³
3	IO	V31
3	IO	V32 ³
3	IO	W33
3	IO	AB25 ³
3	IO	AB26 ³
3	IO	AB31 ³
3	IO	AC31 ³
3	IO	AF34
3	IO	AG31 ³
3	IO	AG33 ³
3	IO	AG34
3	IO	AH29 ³
3	IO	AJ30 ³
3	IO_L129P_Y	V26
3	IO_VREF_L129N_Y	V30 ¹
3	IO_L130P_YY	W34
3	IO_L130N_YY	V28
3	IO_L131P_YY	W32
3	IO_VREF_L131N_YY	W30
3	IO_L132P_Y	V29
3	IO_L132N_Y	Y34
3	IO_L133P	W29 ⁵
3	IO_L133N	Y33 ⁴
3	IO_L134P_Y	W26
3	IO_L134N_Y	W28
3	IO_L135P_YY	Y31
3	IO_L135N_YY	Y30

Table 28: FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E

Bank	Pin Description	Pin #
3	IO_L136P_YY	AA34 ⁵
3	IO_L136N_YY	W31 ⁴
3	IO_D4_L137P_YY	AA33
3	IO_VREF_L137N_YY	Y29
3	IO_L138P_Y	W25
3	IO_L138N_Y	AB34
3	IO_L139P_Y	Y28 ⁵
3	IO_L139N_Y	AB33 ⁴
3	IO_L140P_Y	AA30
3	IO_L140N_Y	Y26
3	IO_L141P_YY	Y27
3	IO_L141N_YY	AA31
3	IO_L142P_YY	AA27 ⁵
3	IO_L142N_YY	AA29 ⁴
3	IO_L143P_Y	AB32
3	IO_VREF_L143N_Y	AB29
3	IO_L144P_Y	AA28
3	IO_L144N_Y	AC34
3	IO_L145P	Y25
3	IO_L145N	AD34
3	IO_L146P_Y	AB30
3	IO_L146N_Y	AC33
3	IO_L147P_Y	AA26
3	IO_L147N_Y	AC32
3	IO_L148P_Y	AD33
3	IO_L148N_Y	AB28
3	IO_L149P_YY	AE34
3	IO_D5_L149N_YY	AB27
3	IO_D6_L150P_YY	AE33
3	IO_VREF_L150N_YY	AC30
3	IO_L151P_Y	AA25
3	IO_L151N_Y	AE32
3	IO_L152P_YY	AE31
3	IO_L152N_YY	AD29

Table 28: FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E

Bank	Pin Description	Pin #
6	IO_VREF_L265N_Y	AJ3
6	IO_L265P_Y	AG5
6	IO_L266N_YY	AD9 ⁴
6	IO_L266P_YY	AJ2 ⁵
6	IO_L267N_YY	AC10
6	IO_L267P_YY	AH2
6	IO_L268N_Y	AH3
6	IO_L268P_Y	AF5
6	IO_L269N_Y	AE8 ⁴
6	IO_L269P_Y	AG3 ⁵
6	IO_L270N_Y	AE7
6	IO_L270P_Y	AG2
6	IO_VREF_L271N_YY	AF6
6	IO_L271P_YY	AG1
6	IO_L272N_YY	AC9 ⁴
6	IO_L272P_YY	AG4 ⁵
6	IO_L273N_YY	AE6
6	IO_L273P_YY	AF3
6	IO_VREF_L274N_Y	AF1 ²
6	IO_L274P_Y	AF4
6	IO_L275N	AB10 ⁴
6	IO_L275P	AF2 ⁵
6	IO_L276N_Y	AC8
6	IO_L276P_Y	AE1
6	IO_VREF_L277N_YY	AD5
6	IO_L277P_YY	AE3
6	IO_L278N_YY	AC7
6	IO_L278P_YY	AD1
6	IO_L279N_Y	AD6
6	IO_L279P_Y	AD2
6	IO_VREF_L280N_YY	AB8
6	IO_L280P_YY	AC1
6	IO_L281N_YY	AC5
6	IO_L281P_YY	AC2

Table 28: FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E

Bank	Pin Description	Pin #
6	IO_L282N_Y	AA9
6	IO_L282P_Y	AC3
6	IO_L283N_Y	AC4
6	IO_L283P_Y	AD4
6	IO_L284N_Y	AA8
6	IO_L284P_Y	AB6
6	IO_L285N	AB1
6	IO_L285P	Y10
6	IO_L286N_Y	AB2
6	IO_L286P_Y	AA7
6	IO_VREF_L287N_Y	AA4
6	IO_L287P_Y	AA1
6	IO_L288N_YY	Y9 ⁴
6	IO_L288P_YY	AB4 ⁵
6	IO_L289N_YY	AA2
6	IO_L289P_YY	Y8
6	IO_L290N_Y	AA6
6	IO_L290P_Y	AA5
6	IO_L291N_Y	AB3 ⁴
6	IO_L291P_Y	Y7 ⁵
6	IO_L292N_Y	Y1
6	IO_L292P_Y	W10
6	IO_VREF_L293N_YY	Y5
6	IO_L293P_YY	Y2
6	IO_L294N_YY	W9 ⁴
6	IO_L294P_YY	W2 ⁵
6	IO_L295N_YY	W7
6	IO_L295P_YY	Y4
6	IO_L296N_Y	W1
6	IO_L296P_Y	Y6
6	IO_L297N_Y	W6 ⁴
6	IO_L297P_Y	W3 ⁵
6	IO_L298N_Y	V9
6	IO_L298P_Y	W4

Table 28: FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E

Bank	Pin Description	Pin #
NA	GND	AP2
NA	GND	AN3
NA	GND	AM20
NA	GND	AK30
NA	GND	AG8
NA	GND	AC29
NA	GND	Y3
NA	GND	Y32
NA	GND	W21
NA	GND	V21
NA	GND	T8
NA	GND	T27
NA	GND	R21
NA	GND	P21
NA	GND	H19
NA	GND	F29
NA	GND	C11
NA	GND	B3
NA	GND	A32
NA	GND	AP3
NA	GND	AN32
NA	GND	AM24
NA	GND	AJ6
NA	GND	AG16
NA	GND	AA14
NA	GND	Y14
NA	GND	W8
NA	GND	W27
NA	GND	U14
NA	GND	T14
NA	GND	R3
NA	GND	R32
NA	GND	M6
NA	GND	H27

Table 28: FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E

Bank	Pin Description	Pin #
NA	GND	E5
NA	GND	C15
NA	GND	B32
NA	GND	A33
NA	GND	AP7
NA	GND	AN33
NA	GND	AM32
NA	GND	AJ12
NA	GND	AG19
NA	GND	AA15
NA	GND	Y15
NA	GND	W14
NA	GND	V14
NA	GND	U15
NA	GND	T15
NA	GND	R14
NA	GND	P14
NA	GND	M29
NA	GND	G1
NA	GND	E18
NA	GND	C20
NA	GND	B33
NA	GND	A34
NA	GND	AP28
NA	GND	AN34
NA	GND	AM33
NA	GND	AJ23
NA	GND	AG27
NA	GND	AA16
NA	GND	Y16
NA	GND	W15
NA	GND	V15
NA	GND	U16
NA	GND	T16

Table 29: FG1156 Differential Pin Pair Summary:
XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E

Pair	Bank	P Pin	N Pin	AO	Other Functions
111	2	M31	R26	2600 1600	-
112	2	N30	P28	3200 1600 1000	-
113	2	N29	N33	2600 2000 1000	VREF
114	2	T25	N34	3200 2600 2000 1600	-
115	2	P34	R27	3200 2600 2000 1600 1000	-
116	2	P29	P31	3200 2600 1600 1000	-
117	2	P33	T26	3200 2600 2000	-
118	2	R34	R28	2600 2000 1000	-
119	2	N31	N32	2000 1600 1000	D3
120	2	P30	R33	2000 1600	-
121	2	R29	T34	3200 2600 2000 1600 1000	-
122	2	R30	T30	1000	-
123	2	T28	R31	3200 1600	-
124	2	T29	U27	3200 2600 1600 1000	-
125	2	T31	T33	2000 1600 1000	VREF
126	2	U28	T32	2000 1600 1000	-
127	2	U29	U33	3200 2600 1600 1000	VREF
128	2	V33	U31	3200 2600 2000 1600 1000	-
129	3	V26	V30	3200 2600 1600 1000	VREF
130	3	W34	V28	2000 1600 1000	-
131	3	W32	W30	2000 1600 1000	VREF

Table 29: FG1156 Differential Pin Pair Summary:
XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E

Pair	Bank	P Pin	N Pin	AO	Other Functions
132	3	V29	Y34	3200 2600 1600 1000	-
133	3	W29	Y33	3200 1600	-
134	3	W26	W28	1000	-
135	3	Y31	Y30	3200 2600 2000 1600 1000	-
136	3	AA34	W31	2000 1600	-
137	3	AA33	Y29	2000 1600 1000	VREF
138	3	W25	AB34	2600 2000 1000	-
139	3	Y28	AB33	3200 2600 2000	-
140	3	AA30	Y26	3200 2600 1600 1000	-
141	3	Y27	AA31	3200 2600 2000 1600 1000	-
142	3	AA27	AA29	3200 2600 2000 1600	-
143	3	AB32	AB29	2600 2000 1000	VREF
144	3	AA28	AC34	3200 1600 1000	-
145	3	Y25	AD34	2600 1600	-
146	3	AB30	AC33	3200 2600 1600 1000	-
147	3	AA26	AC32	2000 1000	-
148	3	AD33	AB28	3200 2600 2000	-
149	3	AE34	AB27	3200 2600 2000 1600 1000	D5
150	3	AE33	AC30	2000 1600 1000	VREF
151	3	AA25	AE32	3200 1600 1000	-
152	3	AE31	AD29	3200 2600 2000 1600 1000	-

Date	Version	Revision
4/2/01	2.0	- Updated numerous values in Virtex-E Switching Characteristics tables. - Changed pinout table footnotes from "V_{REF} option only" to "V_{REF} or I/O option only" to improve clarity. - Converted file to modularized format. See the Virtex-E Data Sheet section.
7/26/01	2.1	- Changed pinout table footnotes from "V_{REF} or I/O option only" to "V_{REF} or I/O option only; otherwise I/O only" to improve clarity. - Changed designation for pin pair 300 in Table 29 from AO to footnote 9.
10/25/01	2.2	- Changed Table 29 to clarify which devices in the FG1156 package can use each pin pair as an asynchronous output. - Updated references to the XCV3200E device in the FG1156 package.
11/15/01	2.3	Fixed cosmetic error.
07/17/02	2.4	- Added "VREF" to the description for pin B15 in Table 12. - Changed designation for pin pair 129 in Table 15 from AO to "AO in the XCV1000E, 1600E, 2000E". - Data sheet designation upgraded from Preliminary to Production.
03/14/03	2.5	Removed the Virtex-E XCV300E section under Pinout Differences Between Virtex and Virtex-E Families (and revised Table 1), since these differences do not exist.

Virtex-E Data Sheet

The Virtex-E Data Sheet contains the following modules:

- DS022-1, Virtex-E 1.8V FPGAs:
[Introduction and Ordering Information \(Module 1\)](#)
- DS022-2, Virtex-E 1.8V FPGAs:
[Functional Description \(Module 2\)](#)
- DS022-3, Virtex-E 1.8V FPGAs:
[DC and Switching Characteristics \(Module 3\)](#)
- DS022-4, Virtex-E 1.8V FPGAs:
[Pinout Tables \(Module 4\)](#)